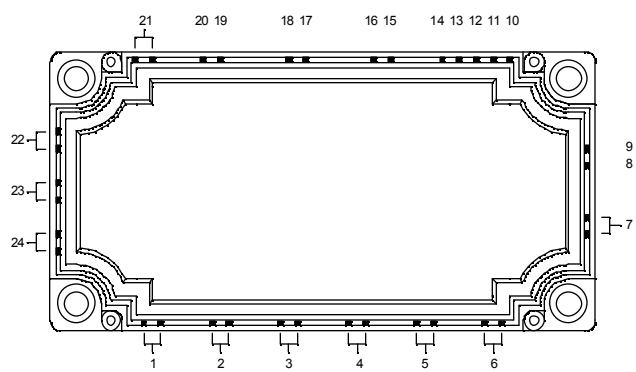
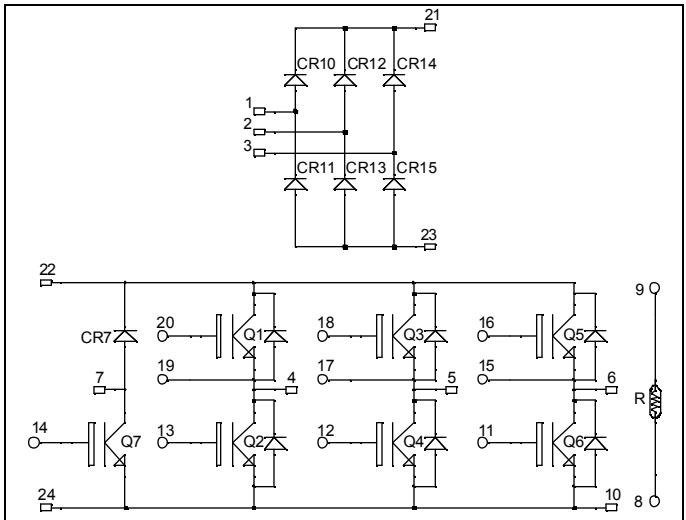


***Input rectifier bridge + Brake + 3 Phase Bridge
Trench + Field Stop IGBT®
Power Module***

$V_{CES} = 1200V$
 $I_C = 75A @ T_c = 80^\circ C$



Application

- AC Motor control

Features

- Trench + Field Stop IGBT® Technology
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 20 kHz
 - Soft recovery parallel diodes
 - Low diode VF
 - Low leakage current
 - Avalanche energy rated
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
- High level of integration
- Internal thermistor for temperature monitoring

Benefits

- Low conduction losses
- Stable temperature behavior
- Very rugged
- Solderable terminals for easy PCB mounting
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive T_C of V_{CEsat}
- Low profile
- RoHS Compliant

All ratings @ $T_j = 25^\circ C$ unless otherwise specified

1. Absolute maximum ratings

Diode rectifier Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1600	V
I_F	DC Forward Current	$T_c = 80^\circ C$ 80	A
I_{FSM}	Surge Forward Current	$T_j = 25^\circ C$ 500	
		$T_j = 150^\circ C$ 400	
		$t_p = 10ms$	

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

IGBT & Diode Brake (only for APTGT75X120BTP3G) Absolute maximum ratings

Symbol	Parameter		Max ratings	Unit
V _{CES}	Collector - Emitter Breakdown Voltage		1200	V
I _C	Continuous Collector Current	T _C = 25°C	55	A
		T _C = 80°C	35	
I _{CM}	Pulsed Collector Current	T _C = 25°C	70	
V _{GE}	Gate – Emitter Voltage		±20	V
P _D	Maximum Power Dissipation	T _C = 25°C	200	W
I _F	DC Forward Current	T _C = 80°C	25	A

IGBT & Diode Inverter Absolute maximum ratings

Symbol	Parameter		Max ratings	Unit
V _{CES}	Collector - Emitter Breakdown Voltage		1200	V
I _C	Continuous Collector Current	T _C = 25°C	105	A
		T _C = 80°C	75	
I _{CM}	Pulsed Collector Current	T _C = 25°C	150	
V _{GE}	Gate – Emitter Voltage		±20	V
P _D	Maximum Power Dissipation	T _C = 25°C	350	W
RBSOA	Reverse Bias Safe Operating Area	T _j = 125°C	150A @ 1100V	
I _F	DC Forward Current	T _C = 80°C	75	A
I _{FRM}	Repetitive Peak Forward Current	t _p = 1ms	150	

2. Electrical Characteristics

Diodes Rectifier Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I _R	Reverse Current	V _R = 1600V	T _j = 150°C	3		mA
V _F	Forward Voltage	I _F = 75A	T _j = 150°C	1.1		V
R _{thJC}	Junction to Case Thermal Resistance				0.65	°C/W

IGBT Brake & Diode (only for APTGT75X120BTP3G) Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I _{CES}	Zero Gate Voltage Collector Current	V _{GE} = 0V, V _{CE} = 1200V			250	μA
V _{CE(sat)}	Collector Emitter on Voltage	V _{GE} = 15V	T _j = 25°C	1.4	1.7	2.1
		I _C = 35A	T _j = 125°C		2.0	
V _{GE(th)}	Gate Threshold Voltage	V _{GE} = V _{CE} , I _C = 2mA	5.0	5.8	6.5	V
I _{GES}	Gate – Emitter Leakage Current	V _{GE} = 20V, V _{CE} = 0V			600	nA
C _{ies}	Input Capacitance	V _{GE} = 0V		2500		pF
C _{oes}	Output Capacitance	V _{CE} = 25V		132		
C _{res}	Reverse Transfer Capacitance	f = 1MHz		115		
V _F	Forward Voltage	V _{GE} = 0V	T _j = 25°C	1.6		V
		I _F = 25A	T _j = 125°C		1.6	
R _{thJC}	Junction to Case Thermal Resistance		IGBT		0.6	°C/W
			Diode		1.2	

IGBT & Diode Inverter Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit	
I _{CES}	Zero Gate Voltage Collector Current	V _{GE} = 0V, V _{CE} = 1200V			250	250	μA	
V _{CE(sat)}	Collector Emitter on Voltage	V _{GE} = 15V	T _j = 25°C		1.7	2.1	V	
		I _C = 75A	T _j = 125°C		2.0			
V _{GE(th)}	Gate Threshold Voltage	V _{GE} = V _{CE} , I _C = 3 mA		5.0	5.8	6.5	V	
I _{GES}	Gate – Emitter Leakage Current	V _{GE} = 20V, V _{CE} = 0V			500	500	nA	
C _{ies}	Input Capacitance	V _{GE} = 0V V _{CE} = 25V f = 1MHz		5345			pF	
C _{oss}	Output Capacitance			280				
C _{rss}	Reverse Transfer Capacitance			242				
T _{d(on)}	Turn-on Delay Time	Inductive Switching (25°C) V _{GE} = ±15V V _{Bus} = 600V I _C = 75A R _G = 4.7Ω		260			ns	
T _r	Rise Time			30				
T _{d(off)}	Turn-off Delay Time			420				
T _f	Fall Time			65				
T _{d(on)}	Turn-on Delay Time	Inductive Switching (125°C) V _{GE} = ±15V V _{Bus} = 600V I _C = 75A R _G = 4.7Ω		285			ns	
T _r	Rise Time			45				
T _{d(off)}	Turn-off Delay Time			520				
T _f	Fall Time			90				
E _{on}	Turn on Energy	V _{GE} = ±15V V _{Bus} = 600V I _C = 75A R _G = 4.7Ω	T _j = 125°C		9.4		mJ	
E _{off}	Turn off Energy		T _j = 125°C		9.4			
V _F	Forward Voltage	V _{GE} = 0V I _F = 75A	T _j = 25°C		1.6	2.2	V	
			T _j = 125°C		1.6			
Q _{rr}	Reverse Recovery Charge	I _F = 75A V _R = 600V di/dt=2000A/μs	T _j = 25°C		8		μC	
			T _j = 125°C		14			
E _r	Reverse Recovery Energy		T _j = 25°C		3		mJ	
			T _j = 125°C		5.5			
R _{thJC}	Junction to Case Thermal Resistance		IGBT			0.35	°C/W	
			Diode			0.58		

Temperature sensor NTC

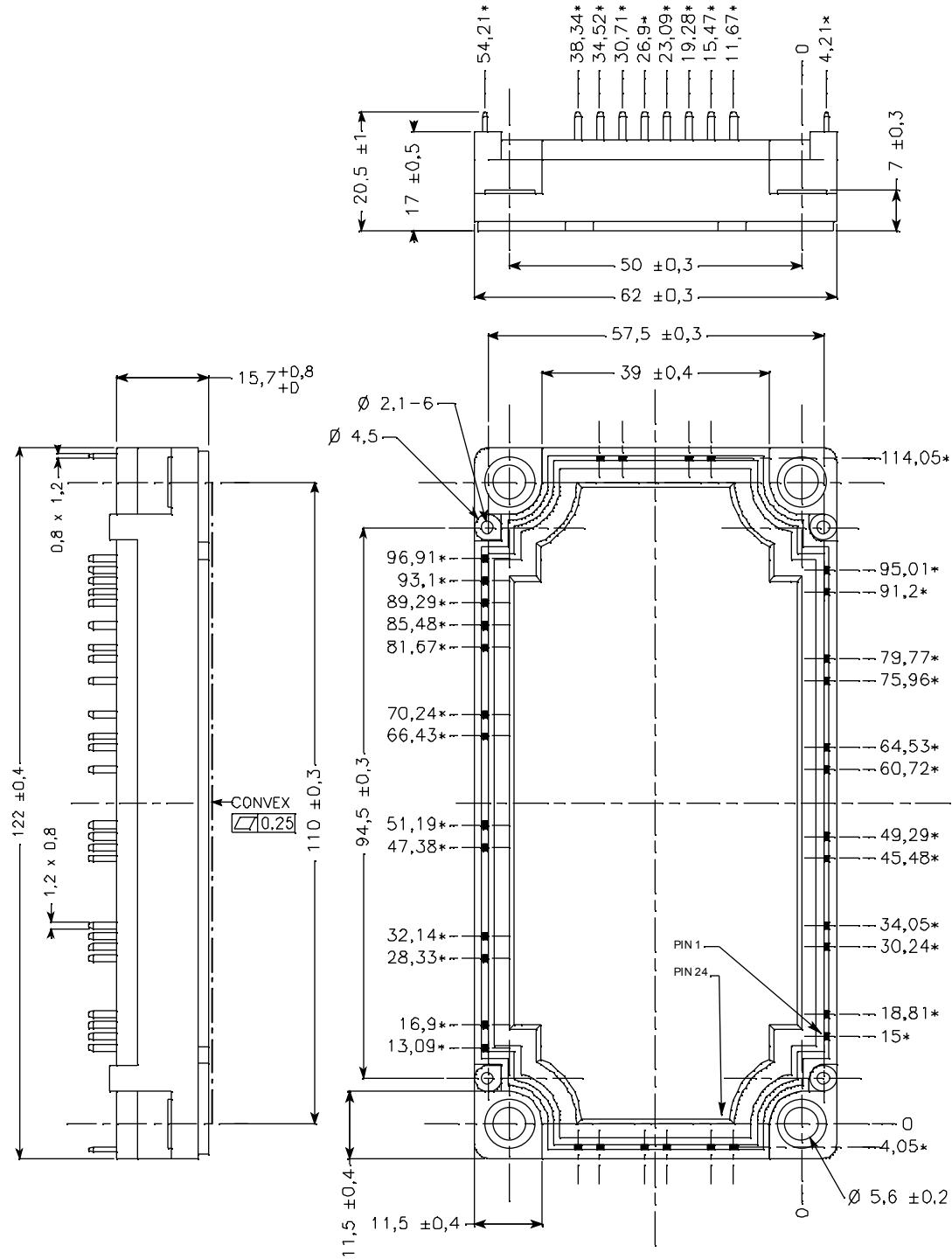
Symbol	Characteristic		Min	Typ	Max	Unit
R ₂₅	Resistance @ 25°C			5		kΩ
B _{25/50}	T ₂₅ = 298.16 K			3375		K

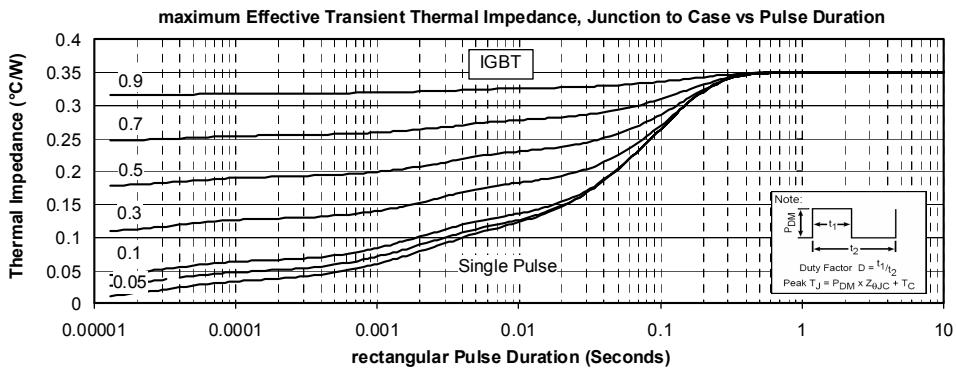
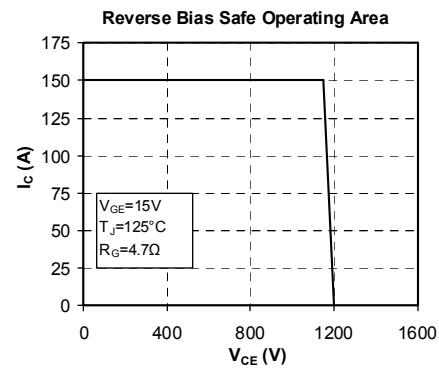
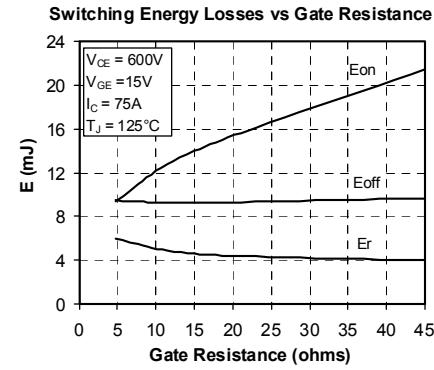
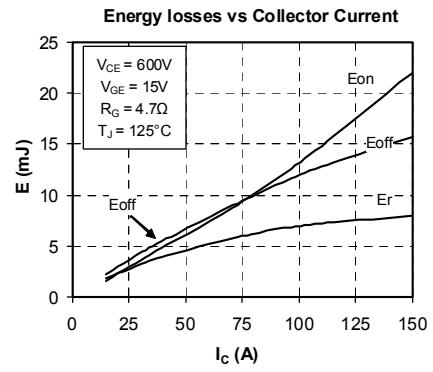
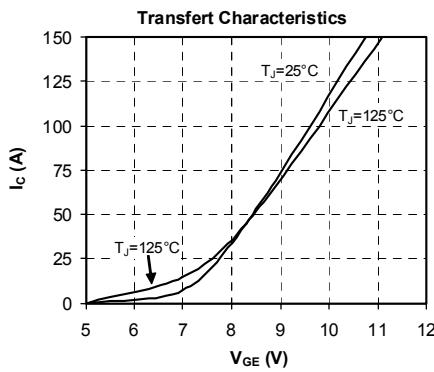
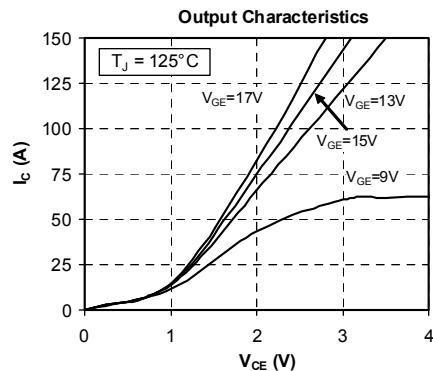
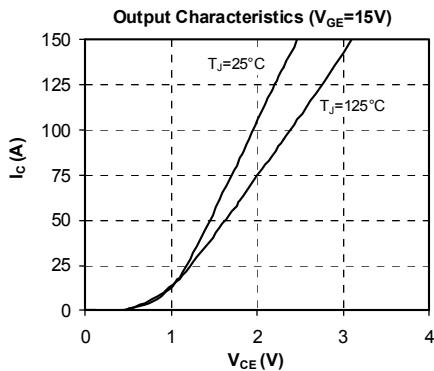
$$R_T = \frac{R_{25}}{\exp\left[B_{25/50}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

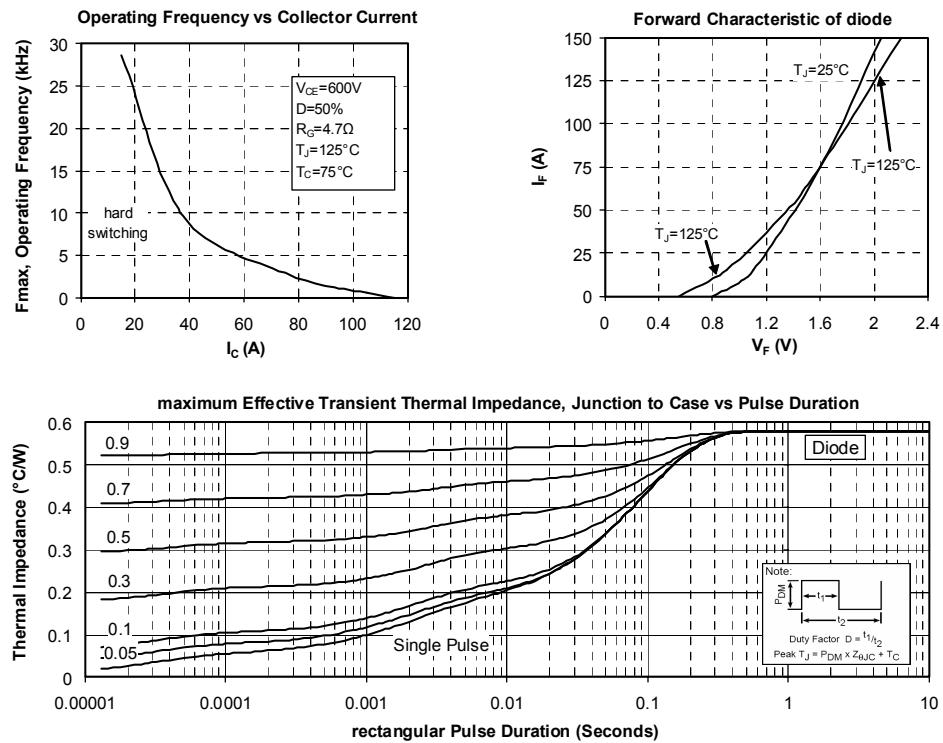
T: Thermistor temperature
R_T: Thermistor value at T

3. Thermal and package characteristics

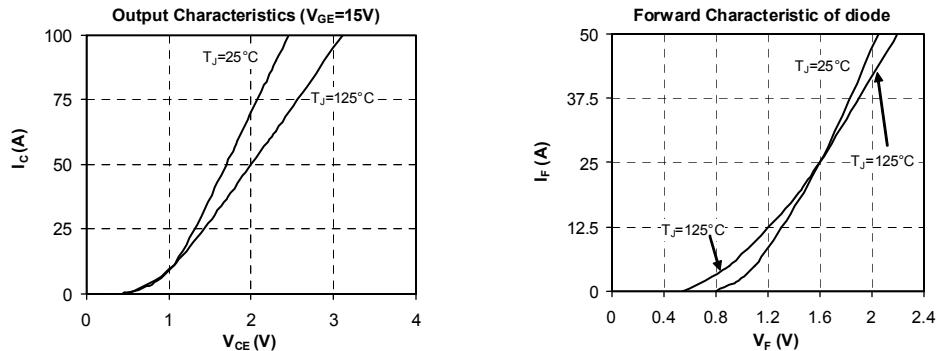
Symbol	Characteristic		Min	Typ	Max	Unit
V _{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, I isol<1mA, 50/60Hz		2500			V
T _J	Operating junction temperature range		-40		150	°C
T _{STG}	Storage Temperature Range		-40		125	
T _C	Operating Case Temperature		-40		125	
Torque	Mounting torque	To Heatsink	M5	2.5	4.7	N.m
Wt	Package Weight				300	g

4. P3 Package outline (dimensions in mm)

 ALL DIMENSIONS MARKED " * " ARE TOLERENCED AS : $\pm 0,4$

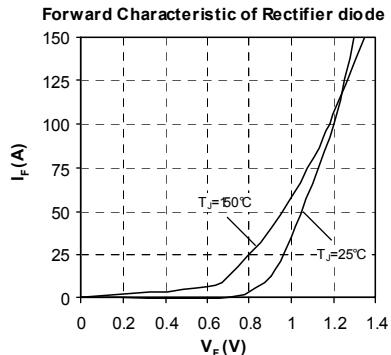
Inverter Typical Performance Curve




Brake Typical Performance Curve



Rectifier Typical Performance Curve



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